



DESCRIPTION:

The products are 6-pin optical relays. The device combines an AlGaAs infrared emitting diode input stage optically coupled to a high-voltage output detector circuit. The detector consists of a high-speed photovoltaic diode array and driver circuitry. The products are widely used in accumulation, automotive battery management system, automobile battery and power system insulation testing, industrial controls and EMR/reed relay replacement.

MAIN FEATURES:

High isolation 5000 Vrms

Single channel normally open Single-Pole-Single-Throw Relay

Operating temperature range -40°C to 110°C

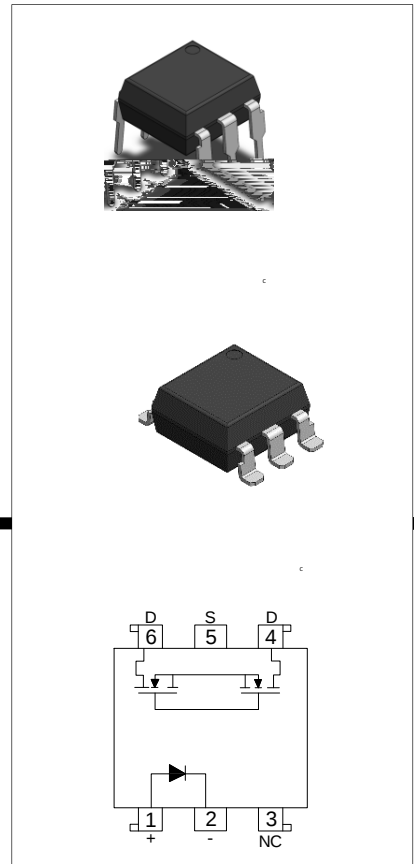
REACH & RoHS compliance

HBM: H3A; MM: M4; CDM: C3

CQC approved

VDE approved

UL approved



ABSOLUTE MAXIMUM RATINGS (Temperature=25°C)

Input	Forward Current	I_F	50	mA
	Peak Forward Current	I_{FP}	1	A
	Reverse Voltage	V_R	6	V
	Power Dissipation	P_D	75	mW
Output	Switching Voltage	V_O	40	V
	Continuous Load Current	I_O	3.5	A
	Power Dissipation	P_C	360	mW
Operating Temperature		T_{opr}	-40~110	
Junction Temperature		T_j	125	
Storage Temperature		T_{stg}	-55~125	
Total Power Dissipation		P_{tot}	450	mW
Isolation Voltage		V_{iso}	5000	Vrms

Soldering Temperature	T_{soll}	210
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NOTE1:

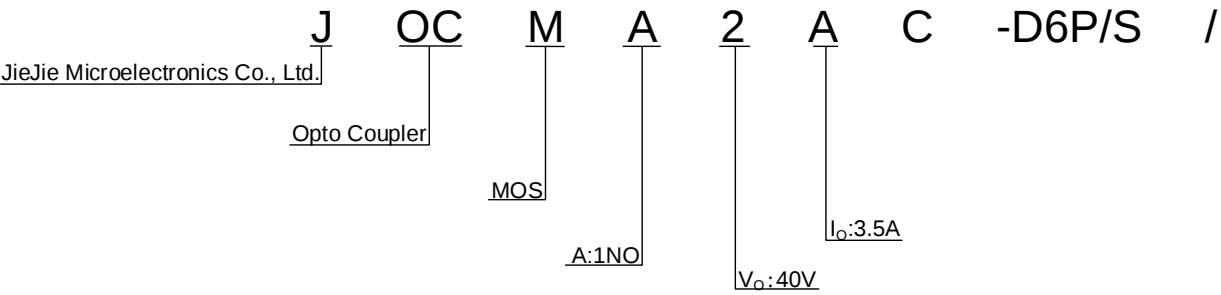
NOTE2:

ELECTRICAL CHARACTERISTICS (Temperature=25°C)

Input	Forward Voltage	V_F	$I_F=10mA$	-	1.35	1.5	V
	Reverse Current	I_R	$V_R=6V$	-	-	1	μA
	Terminal Capacitance	C_t	$V=0,f=1MHz$	-	70	-	pF
	LED Trigger Current	I_{FT}	$I_O=I_{O(MAX)}$	-	-	3	mA
	Reset Current	$I_{F(OFF)}$	$I_O=I_{O(MAX)}$	0.1	- X	- *	mA
Output	Open-circuit leakage current	$I_{Leak \bar{A}}$	θ		N		



ORDERING INFORMATION

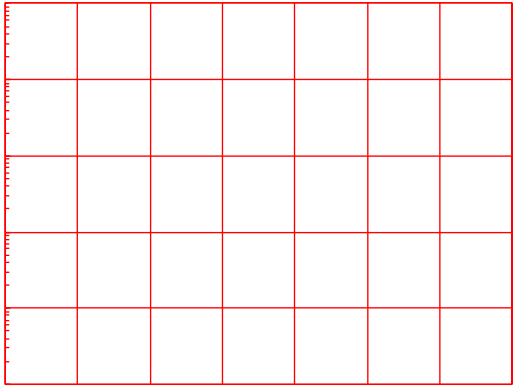




Characteristics Curves

Forward Current vs. Forward Voltage

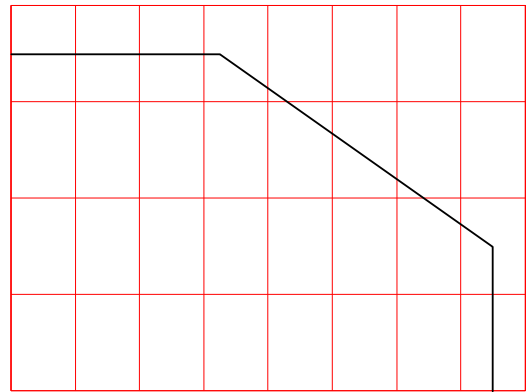
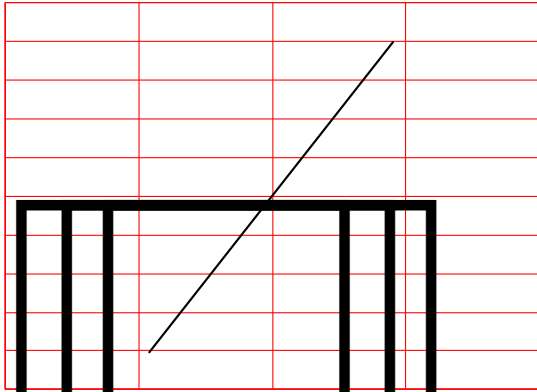
Max. Allowable LED Forward Current
vs. Ambient Temperature





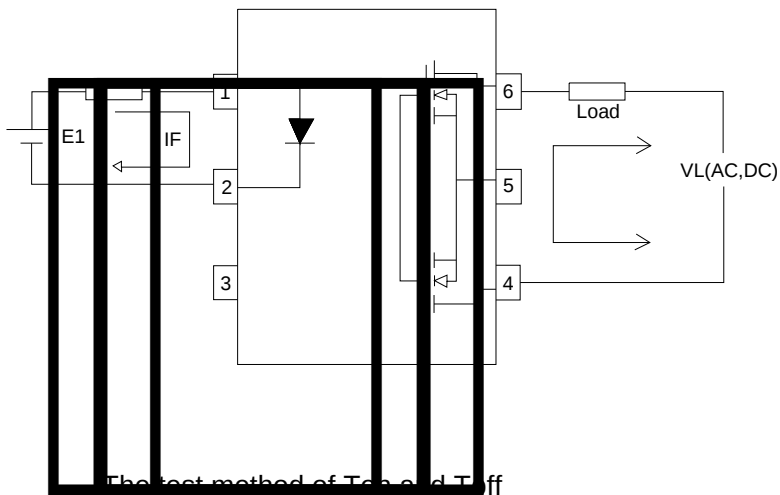
Output Current vs. Output Voltage

Output Current vs. Amplifier Temperature

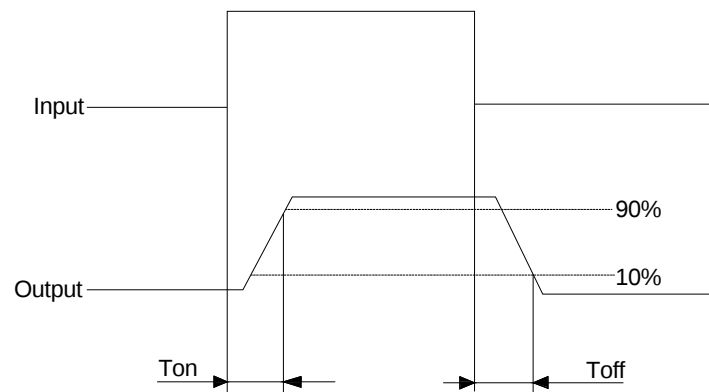
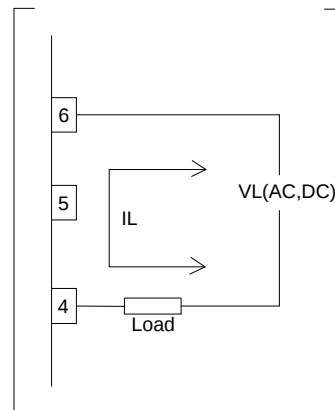


TEST CIRCUITS

Wiring diagram

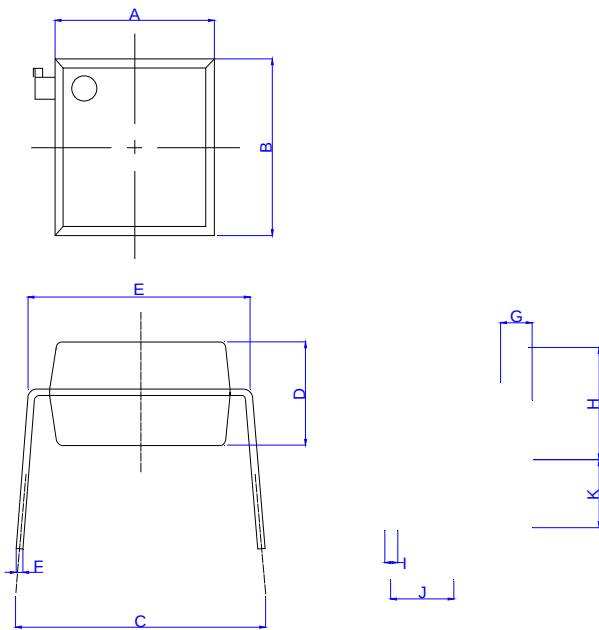


The test method of Ton and Toff





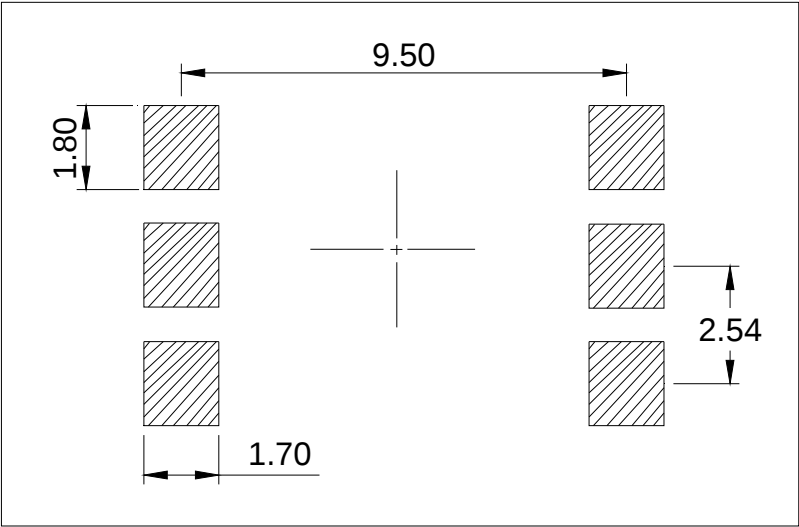
Package Dimension (Unit: mm)



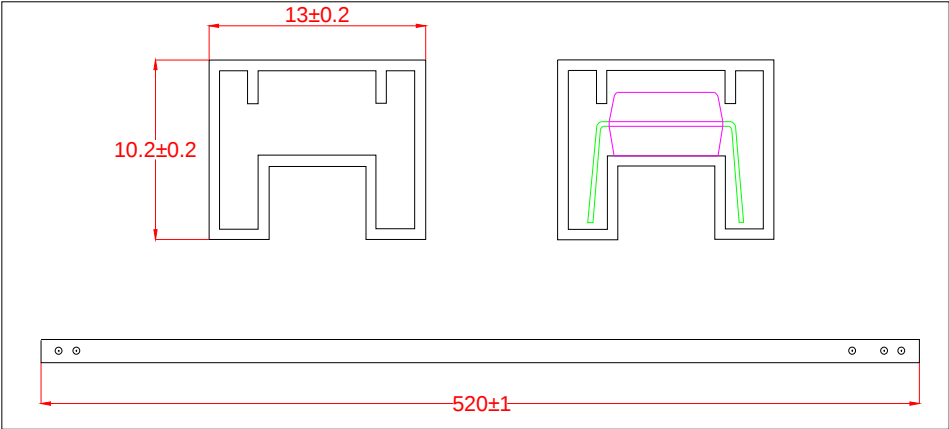
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	6.20		6.60	0.244		0.260
B	6.92		7.32	0.272		0.288
C	7.15		8.95	0.281		0.352
D	3.20		3.60	0.126		0.142
E	7.32		7.92	0.288		0.312
F						
G	1.15		1.35	0.045		0.053
H	3.90		4.50	0.154		0.177
I						
J						
K						



RECOMMENDED SOLDER MASK (Dimensions in mm unless otherwise stated)

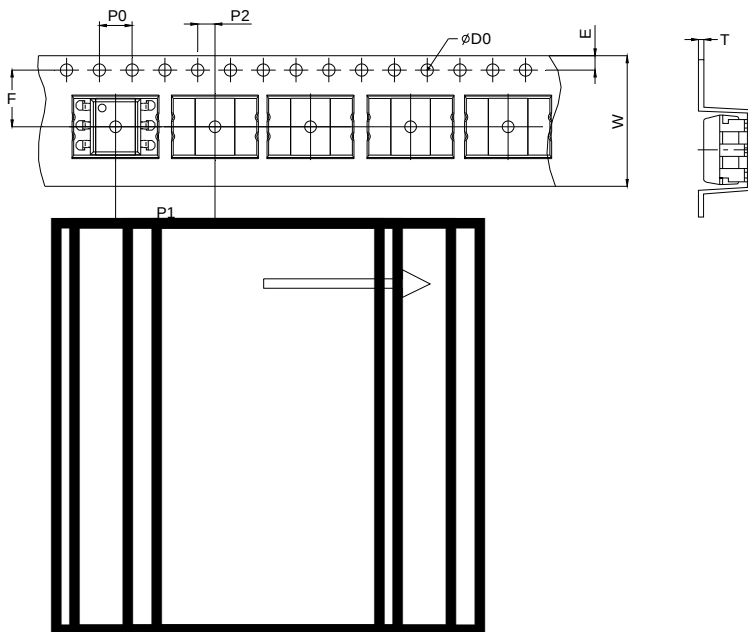


TUBE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

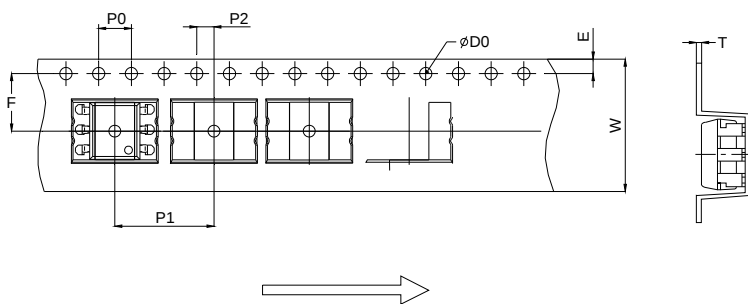




CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

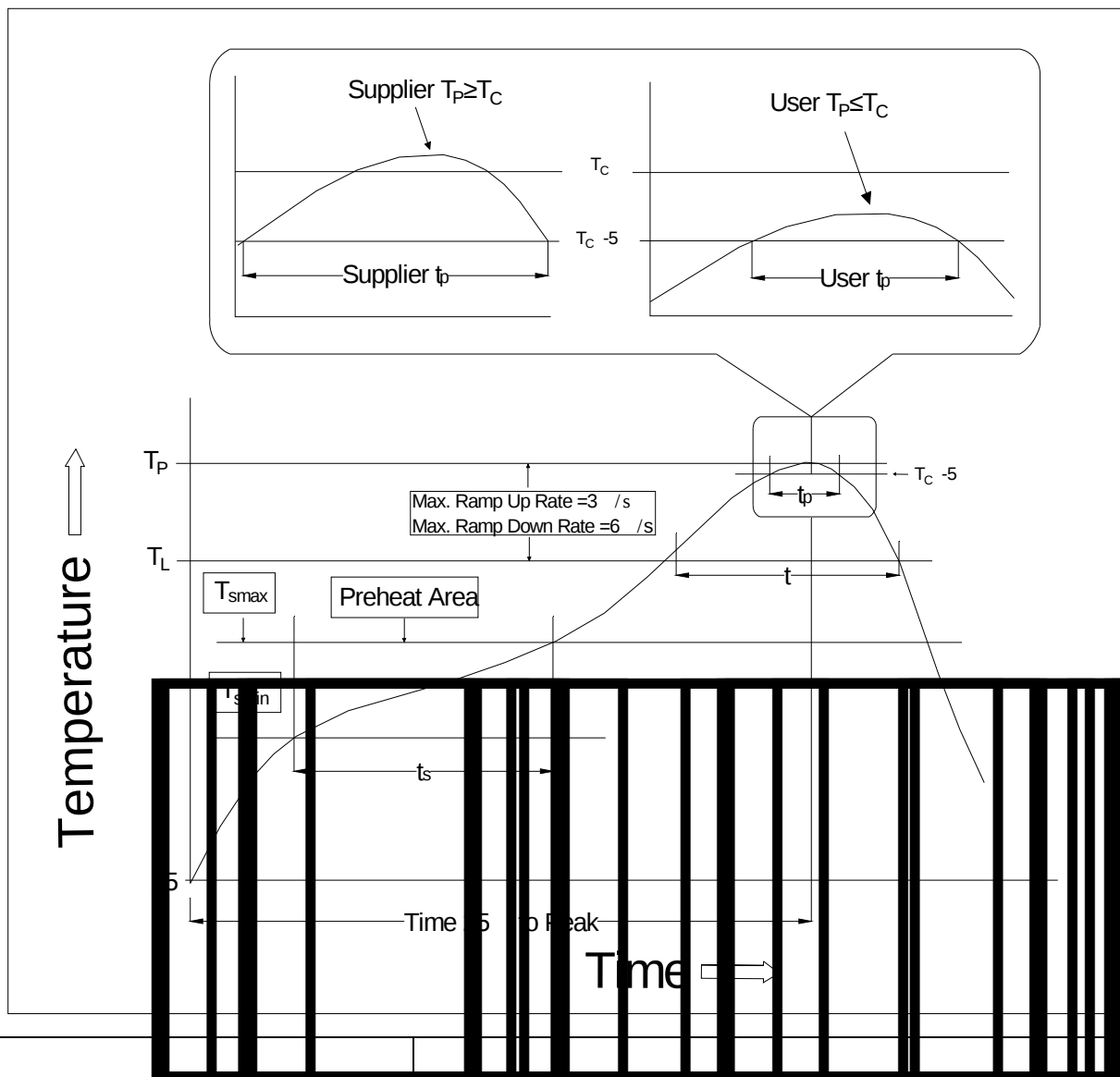


Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0		1.50	1.60		0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	11.90	12.00	12.10	0.469	0.472	0.476
P2	1.90	2.00	2.10	0.075	0.079	0.083
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
T	0.35	0.40	0.45	0.014	0.016	0.018
W	15.70	16.00	16.30	0.618	0.630	0.642



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0		1.50	1.60		0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	11.90	12.00	12.10	0.469	0.472	0.476
P2	1.90	2.00	2.10	0.075	0.079	0.083
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
T	0.35	0.40	0.45	0.014	0.016	0.018
W	15.70	16.00	16.30	0.618	0.630	0.642

REFLOW INFORMATION



Temperature Min. (T _{smin})	100	150
Temperature Max. (T _{smax})	150	200
Time (t _s) from (T _{smin} to T _{smax})	60-120 seconds	60-120 seconds
Ramp-up Rate (t _L to t _P)	3 °/second max.	3 °/second max.
Liquidus Temperature (T _L)	183	217
Time (t _L) Maintained Above (T _L)	60-150 seconds	60-150 seconds
Peak Body Package Temperature	235 +0 /-5	260 +0 /-5
Time (t _P) within 5 ° of 260	10 seconds	10 seconds
Ramp-down Rate (T _P to T _L)	3-6 °/second	3-6 °/second
Time 25 ° to Peak Temperature	6 minutes max.	8 minutes max.



Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.
2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.
3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.
4. Ensure the component has cooled to ambient temperature before proceeding with any subsequent manufacturing steps.
5. The component has a shelf life of 3 months in specification